

Docket No.: I432.105.101/P27509

11-05-2004



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ice:  
s) thereof.

10-28-04

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## 1. Name of conveying party(ies):

Michael Specht; and  
Franz Hofmann

## 2. Name and address of receiving party(ies):

Name: Infineon Technologies AG

Internal Address:

Street Address: St. Martin Str. 53

City: Munich State: ZIP: 81541

Country: Germany

Additional name(s) &amp; addresses attached?

☐ Yes ☒ No

Additional name(s) of conveying party(ies) attached?

☒ No ☐ Yes

## 3. Nature of conveyance:

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date: September 28, 2004; and September 28, 2004

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

A. Patent Application Serial No.(s)/Filing Date(s)

10/486,184

February 6, 2004

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Paul P. Kempf

## 6. Total number of applications and patents involved: 1

## 7. Total fee (37 CFR 3.41). . \$40.00

☐ Enclosed.☒ The Patent Office is hereby authorized to charge Deposit Acct. No. 50-0471 in the amount of \$40.00 for recording of the Assignment document.☒ Any deficiencies in enclosed fees should be charged to deposit account 50-0471.

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100 South Fifth Street

Minneapolis, MN 55402

8. Deposit Account Number: 50-0471

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Paul P. Kempf

(Name of Person Signing)

Signature

Date

10/25/04

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PATENT  
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INFINEON REF NO. P27509  
O.C. REF NO. I432.105.101

## ASSIGNMENT

For good and valuable consideration, I, Michael Specht, a citizen of Deutschland, residing at Schraudolphstraße 42, 80799 München, Deutschland; and Franz Hofmann, a citizen of Deutschland, residing at Herbergstraße 25B, 80995 München, Deutschland; hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies AG, a corporation organized and existing under the laws of Germany, having its principal place of business at St. Martin Str. 53, 81541, Munich, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and may be identified in the United States Patent Office by International Application Number PCT/DE02/03220, which entered the U.S. National Stage on February 6, 2004 under U.S. Application No. 10/486,184,

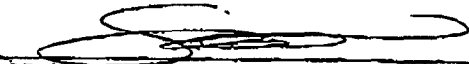
entitled: SEMICONDUCTOR MEMORY ELEMENT, SEMICONDUCTOR MEMORY ELEMENT ARRANGEMENT, METHOD FOR FABRICATING A SEMICONDUCTOR MEMORY ELEMENT AND METHOD FOR OPERATING A SEMICONDUCTOR MEMORY ELEMENT

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

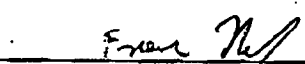
Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE:

  
NAME: Michael Specht

DATE: 28/9/04

SIGNATURE:

  
NAME: Franz Hofmann

DATE: 28/09/04